

Layer Stack Up Detail for: AIP041A.PcbDoc

Layer Name	Gerber Document	Copper Thickness	Dielectric Material
Top Solder Mask	(.GTS)		Solder Resist
Top Layer	(.GTL)	1.4mil	FR-4
Bottom Layer	(.GBL)	1.4mil	
Bottom Solder Mask (.GBS)			Solder Resist

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL
 MIN. CLEARANCE: 0.2 mm
 MIN. VIA PAD SIZE: 24 MIL
 MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
 PER IPC-D-275 CLASS 2 LEVEL C
 REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:

☐ FR-408 ☒ FR-4 High Tg ☐ OTHER _____
 THICKNESS: ☒ 62 MIL (1.6mm) +/-10% ☐ OTHER _____
 TOLERANCE: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/- _____
 BOW & TWIST: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/- _____

DRILLING:

REFERENCE: ☒ AS SHOWN ☒ NC_DRILL FILES
 PTH MIN COPPER THICKNESS: ☒ 1MIL ☐ OTHER _____

BOARD FINISH:

SILKSCREEN: ☒ TOP ☐ BOTTOM
 SILKSCREEN COLOR: ☒ WHITE ☐ OTHER _____
 SOLDER RESIST COLOR:
☒ GREEN ☐ BLUE ☐ OTHER _____

SURFACE FINISH: ☒ IMMERSION GOLD (ENIG) ☐ ENERPIG

☐ IMM. TIN/SILVER OR EQUIV ☐ OTHER _____

ARRAY/PANEL: ☐ CUT AND TRM PER MECH LAYER 1
☐ N.C. ROUTE ☒ V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs

TO MEET OR EXCEED THE REQUIREMENTS OF:
☒ ANSI IPC-A-600F CLASS -> ☐ 1 ☒ 2 ☐ 3
☒ UL 94V-0 ☒ RoHS ☐ OTHER PER ORDER

ADDITIONAL REQUIREMENTS:

MICROSECTION: ☐ YES
 BARE BOARD ELEC. TEST: ☐ NONE ☒ REQUIRED ☐ PER ORDER
 MANUFACTURER'S UL: ☐ RAL ☐ METAL ☒ SLK



PROJECT TITLE:

DRU2700EUM-HV500

DESIGNED FOR:

Public Release

FILE NAME:

AIP041A.PcbDoc

ENGINEER:

Rodney Miranda

LAYOUT BY:

Rodney Miranda

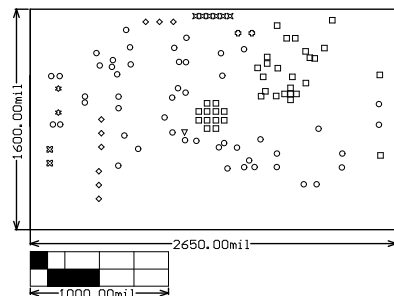
SCALE: 0.72

ALTIM DESIGNER VERSION:

10.0.0.27009

Drill Table

Symbol	Hit Count	Tool Size	Plated	Hole Type
□	34	7.874mil (0.2mm)	PTH	Round
▽	1	10mil (0.254mm)	PTH	Round
◇	48	15mil (0.381mm)	PTH	Round
⊗	2	18mil (0.457mm)	NPTH	Round
⊕	6	24mil (0.61mm)	PTH	Round
⊙	9	39.37mil (1mm)	PTH	Round
⊖	2	40.157mil (1.02mm)	PTH	Round
⊗	2	43.307mil (1.1mm)	PTH	Round
⊕	2	51.181mil (1.3mm)	PTH	Round
□	3	63mil (1.6mm)	PTH	Round
	109 Total			



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: AIP041	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Microsection			
PLOT NAME = Fabrication Drawing	GENERATED : 3/27/2015 2:20:03 PM	TEXAS INSTRUMENTS	

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